WHAT IS CLAIMED IS:

1. A method for forming an electrolytic copper plating on an R-T-B magnet, wherein R is at least one of rare earth elements including Y, and T is Fe or Fe and Co, comprising using an electrolytic copper plating solution containing 20-150 g/L of copper sulfate and 30-250 g/L of a chelating agent without containing an agent for reducing a copper ion, the pH of said electrolytic copper plating solution being controlled to 10.5-13.5.

2. The method for forming an electrolytic copper plating on an R-T-B magnet according to claim 1, wherein ethylenediaminetetraacetic acid (EDTA) is used as said chelating agent.

3. The method for forming an electrolytic copper plating on an R-T-B magnet according to claim 1 or 2, wherein said agent for reducing copper ions is formaldehyde.

4. The method for forming an electrolytic copper plating on an R-T-B magnet according to any one of claims 1-3, wherein said R-T-B magnet contains as a main phase an $R_2T_{14}B$ intermetallic compound, wherein R is at least one of rare earth elements including Y, and T is Fe or Fe and Co.

5. An R-T-B magnet having an electrolytic copper plating layer, in which a ratio of I(200)/I(111), wherein I(200) is an X-ray diffraction peak intensity of a (200) face, and I(111) is an X-ray diffraction peak intensity of a (111) face, is 0.1-0.45 in the X-ray diffraction of said electrolytic copper plating layer obtained with a CuKα1 line.

6. The R-T-B magnet according to claim 5, comprising a first layer of said electrolytic copper plating layer, and a second layer formed on said first layer, said second layer being a plating layer comprising at least one selected from the group consisting of Ni, Ni-Cu alloys, Ni-Sn alloys, Ni-Zn alloys, Sn-Pb alloys, Sn, Pb, Zn, Zn-Fe alloys, Zn-Sn alloys, Co, Cd, Au,

Pd and Ag.

7. The R-T-B magnet according to claim 6, wherein said the second layer is constituted by an electrolytic or electroless nickel plating layer.

8. The R-T-B magnet according to any one of claims 5-7, wherein said electrolytic copper plating layer has pinholes in the number of $0/cm^2$ when measured by a ferroxyl test method (JIS H 8617), and further has a Vickers hardness of 260-350.

9. The R-T-B magnet according to any one of claims 5-8, wherein a chemical conversion coating layer is formed on a plating layer constituted by said second layer.

10. The R-T-B magnet according to claim 9, wherein a surface of said chemical conversion coating layer is subjected to an alkali treatment.

11. An R-T-B magnet with a plating layer, wherein R is at least one of rare earth elements including Y, and T is Fe or Fe and Co, wherein said plating layer comprises an electrolytic copper plating layer and an electrolytic or electroless nickel plating layer in this order from the magnet side; wherein a ratio of I(200)/I(111), wherein I(200) is an X-ray diffraction peak intensity of a (200) face, and I(111) is an X-ray diffraction peak intensity of a (111) face, is 0.1-0.45 in the X-ray diffraction of said electrolytic copper plating layer obtained with a CuKα1 line, and wherein said electrolytic copper plating layer is formed by an electrolytic copper plating method using an electrolytic copper plating solution containing 20-150 g/L of copper sulfate and 30-250 g/L of a chelating agent without containing an agent for reducing a copper ion, the pH of said electrolytic copper plating solution being controlled to 10.5-13.5.

12. The R-T-B magnet according to any one of claims 5-10, wherein it is used for a rotor or an actuator.

13. The R-T-B magnet according to claim 11, wherein it is used for a

rotor or an actuator.